



P1K0.0805.3FC.B

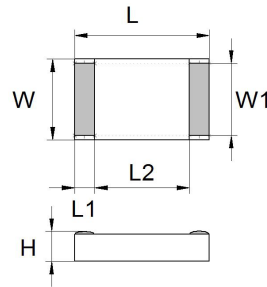
FlipChip platinum sensor

For the automatic assembling on PCB by soldering or bonding

Benefits & Characteristics

- Excellent long-term stability
- Low self-heating
- Fast response time
- Minimum space consumption on PCB
- Optimal price-performance ratio

Illustration¹⁾

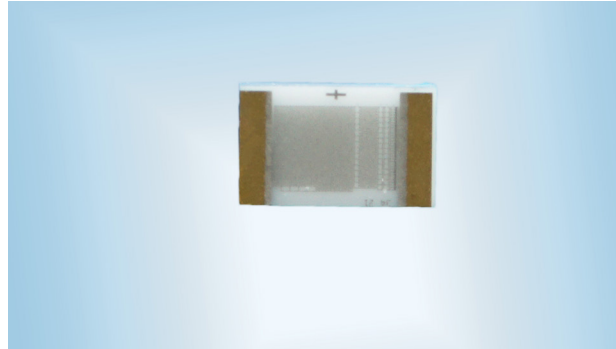


Technical Data

Operating temperature range:	-50 °C to +250 °C
Nominal resistance:	1000 Ω at 0 °C
Characteristics curve:	3850 ppm/K
Long-term stability:	< 0.04 % at 1000 h at 130 °C
Tolerance class (dependent on temperature range):	IEC 60751 F0.3 B (IST AG reference)
Connection:	Au-Pads (solderable and bondable pads)
Dimensions:	1.9 / 0.25 / 1.4 x 1.15 / 1.1 x 0.45
Tolerance:	±0.2 mm (H ±0.15)
Solderability:	235 °C ≤ 8 s (DIN IEC 68 T2-20, Ta Meth. 1)
Resistance to soldering heat: ¹⁾	260 °C 10 s (DIN IEC 68 T2-20, Ta Meth. 1A)
Recommended applied current: ²⁾	0.3 mA at 1000 Ω
Packaging:	< 100 pcs in trays



Product Photo



Order Information

Description:	Item number:	Former main reference:
P1K0.0805.3FC.B	101246	010.02749

Additional Documents

Application Note:	Document name:
	ATP_E

